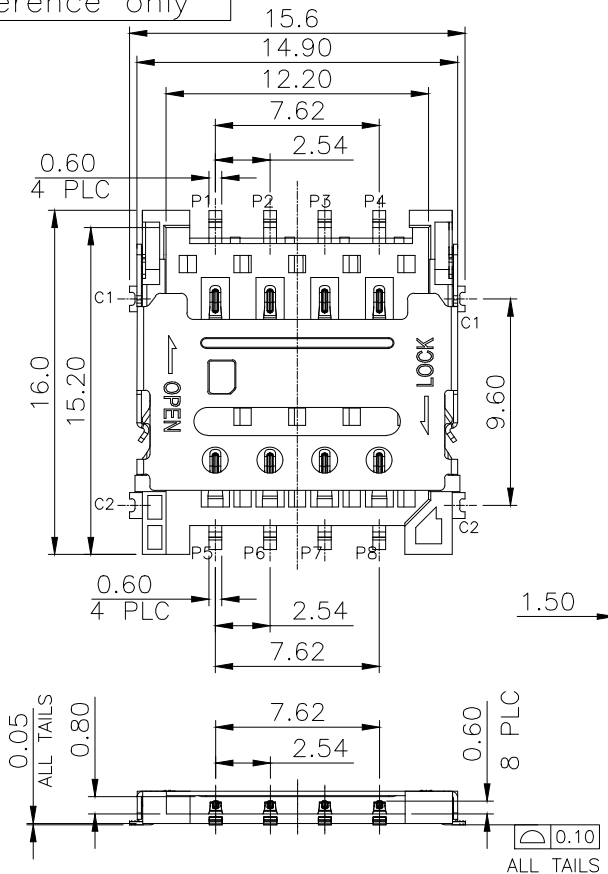


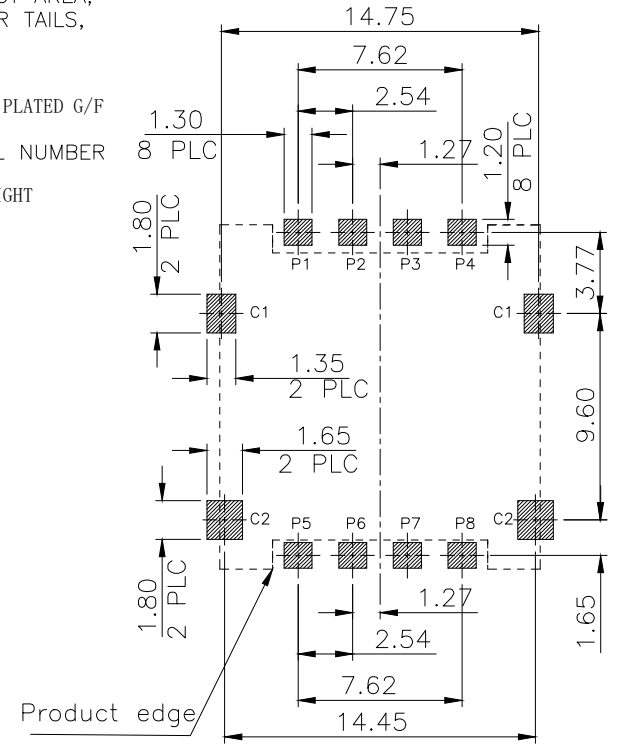
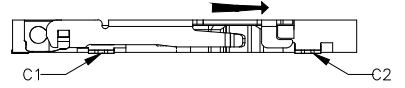
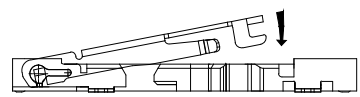
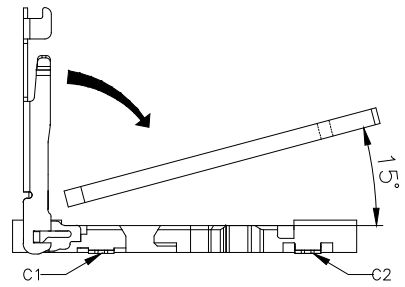
Customer drawings
Reference only

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2017/10/18

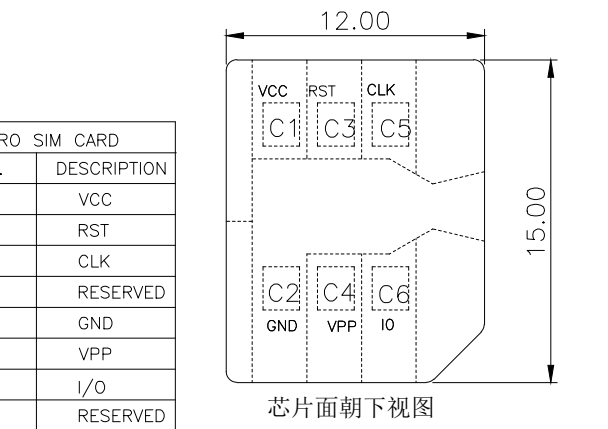


NOTES:

- MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
CONTACT:COPPER ALLOY
SHELL:STAINLESS STEEL
- FINISH:
CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS,
- PART NO.: C-S3 08 150 A1-1
C: CARD TYPE 1: GOLD PLATED G/F
S3: MICRO SIM CARD A1: SERIAL NUMBER
08: 8Pin 150: 1.50mm HEIGHT



RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05



芯片面朝下视图

MICRO SIM CARD	
PIN NO.	DESCRIPTION
P1	VCC
P2	RST
P3	CLK
P4	RESERVED
P5	GND
P6	VPP
P7	I/O
P8	RESERVED

GENERAL TOLERANCE		DWG NO.	APPD:	彭善平	Scale	1:1
X.±0.45	x.'±5°	Title	CHKD:	Vaskov	UNIT	mm
.X±0.35	.x'±2°		DR:			
.XX±0.25	.xx'±1°	Part NO.	Date	2017/10/18		
.XXX±0.15	.xxx'±0.5°					
SHEET	1/1	东莞市铭标电子科技有限公司 Ming Biao Electronic Technology Co., Ltd.				